

PCB Number: XX####
PCB Rev: E1

PCB
LOGO
Texas Instruments

^ You should delete the nylon screws/standoffs and/or the bumpers as needed for your design (or substitute other parts from Hardware.IntLib). Bumpers are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

LBL1
PCB Label
Size: 0.65" x 0.20 "

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Number: XX####	Rev: E1	Designed for: Public Release	Mod. Date: 3/5/2014
SVN Rev: Not in version control	Assembly Variant: 001	Project Title: Change in menu Project Project Options Parameter	Sheet Title:
Drawn By:	File: PMP9374 Hardware_ANSI-B_SchDoc	Sheet: 1 of 1	Size: B
Engineer: Enter name of project lead	Contact: http://www.ti.com/support		



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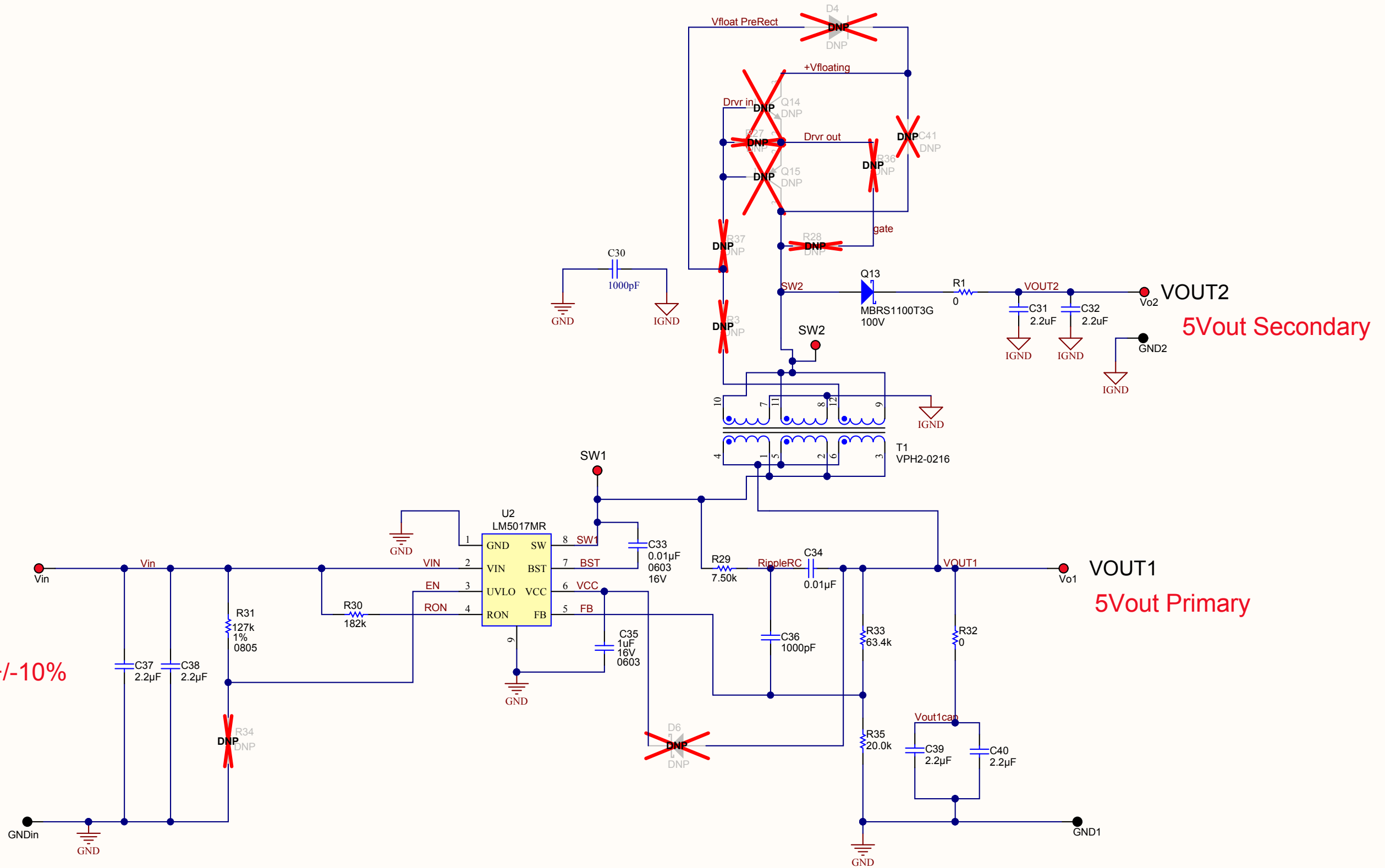
Revision History	
Revision	Notes

Place Block Diagram here (if appropriate) or delete this text box.
 If using a block diagram from another tool, save the picture as a .bmp file.
 Then, use menu Place|Drawing Tools|Graphic to insert the .bmp file on the schematic.

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Number: XX####	Rev: E1	Designed for: Public Release	Mod. Date: 3/5/2014
SVN Rev: Not in version control	Assembly Variant: 001	Project Title: Change in menu Project Project Options Parameter	Sheet: 1 of 1
Drawn By:	File: PMP9374_Cover Sheet_ANSI-B_SchDoc	Sheet Title:	Size: B
Engineer: Enter name of project lead	Contact: http://www.ti.com/support		





Vin = 12Vin +/- 10%

5Vout Secondary

5Vout Primary

Title		
Size	Number	Revision
B		
Date:	3/5/2014	Sheet of
File:	C:\Users\...\PMP9374 Schematics.SchDoc	Drawn By:

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